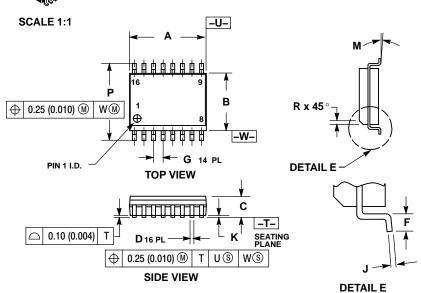
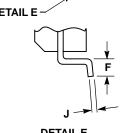
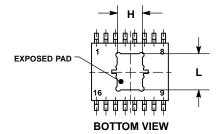
SOIC 16 LEAD WIDE BODY, EXPOSED PAD

CASE 751AG **ISSUE B**

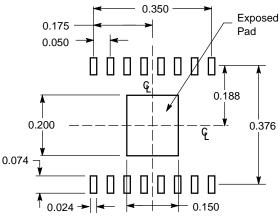
DATE 31 MAY 2016







SOLDERING FOOTPRINT*



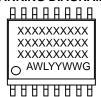
DIMENSIONS: INCHES

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION. 3.
- 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF THE D
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 6. 751R-01 OBSOLETE, NEW STANDARD 751R-02.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	10.15	10.45	0.400	0.411
В	7.40	7.60	0.292	0.299
С	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
Н	3.45	3.66	0.136	0.144
J	0.25	0.32	0.010	0.012
K	0.00	0.10	0.000	0.004
L	4.72	4.93	0.186	0.194
M	0 °	7 °	0 °	7 °
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code

= Assembly Location

= Wafer Lot WL YY = Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

DOCUMENT NUMBER:	98AON21237D	
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION	SOIC_16 WR EXPOSED PAD	

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PAGE 1 OF 2

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



DOCUMENT	NUMBER:
98AON21237	7D

PAGE 2 OF 2

ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. BY P. CELAYA.	26 JUL 2005
Α	CHANGED VALUES OF EXPOSED PAD; DIMS H & L. CHANGED EXPOSED PAD VALUE IN SOLDER FOOTPRINT FROM 0.145 TO 0.150. REQ. BY B. FONTES.	11 MAR 2008
В	CORRECTED DIMENSION D LABELS IN SIDE VIEW. REQ. BY J. LETTERMAN.	31 MAY 2016

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